

**Amendments to the Claims:**

Please cancel claims 10 through 16 and 25 without prejudice or disclaimer.

Claims 1 through 9, 17 through 23 and 26 through 31 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A method of making a cathode assembly of an FED, comprising:  
providing a substrate;  
forming an emitter electrode structure on the substrate;  
forming a resistive layer over the emitter electrode structure;  
forming an insulative layer on a portion of the resistive layer;  
forming at least one micropoint emitter on the substrate and in contact with both the resistive layer and the insulative layer;  
forming a conductive grid structure spaced from the at least one micropoint emitter; and  
forming a dielectric structure spaced from the at least one micropoint emitter and between the insulative layer and the grid structure.
2. (Currently Amended) The method of Claim 1 wherein ~~said~~the emitter electrode structure comprises metal.
3. (Currently Amended) The method of Claim 1 wherein ~~said~~the emitter electrode structure comprises aluminum.
4. (Currently Amended) The method of Claim 1 wherein ~~said~~the resistive layer comprises silicon.

5. (Currently Amended) The method of Claim 1 wherein ~~said~~the insulative layer comprises silicon oxide.

6. (Currently Amended) The method of Claim 1 wherein said insulative layer comprises silicon nitride.

7. (Currently Amended) The method of Claim 1 wherein ~~said~~the insulative layer comprises a strip having a thickness of about 1000 Å.

8. (Currently Amended) The method of Claim 1 wherein ~~said~~the substrate comprises glass.

9. (Currently Amended) The method of Claim 1 wherein forming ~~said~~the conductive grid structure and ~~said~~the dielectric structure comprise:  
depositing a dielectric layer over the insulative layer and ~~said~~the at least one micropoint emitter;  
depositing a conductive layer over the dielectric layer; and  
selectively etching openings through the conductive and dielectric layers to expose the at least one micropoint emitter, with walls defining the openings being spaced away from at least one micropoint emitter.

Claims 10-16 (Canceled).

17. (Currently Amended) ~~In a method of making a field emission device, a~~ A method of making a column line structure for an addressing matrix of a field emission device, comprising:

forming ~~a~~ an elongated conductive structure on a substrate;

forming a resistive layer directly on said a top surface of the elongated conductive structure and over at least a portion of a side surface thereof; ~~wherein the resistive layer is in contact with at least one micropoint emitter formed on a substrate; and~~

forming an insulative layer partly covering said a top surface of the resistive layer and leaving at least a portion of a side surface thereof exposed ~~layer and in contact with the at least one micropoint emitter; and~~

forming a micropoint emitter over the substrate in lateral contact with the resistive layer and the insulative layer.

18. (Currently Amended) The method of Claim 17 wherein ~~said~~ the elongated conductive structure comprises metal.

19. (Currently Amended) The method of Claim 17 wherein ~~said~~ the elongated conductive structure comprises aluminum.

20. (Currently Amended) The method of Claim 17 wherein ~~said~~ the resistive layer comprises silicon.

21. (Currently Amended) The method of Claim 17 wherein ~~said~~ the insulative layer comprises silicon oxide.

22. (Currently Amended) The method of Claim 17 wherein ~~said~~ the insulative layer comprises silicon nitride.

23. (Currently Amended) The method of Claim 17 wherein ~~said~~ the insulative layer comprises a strip having a thickness of about 1000 Å.

Claims 24 and 25 (Canceled).

26. (Currently Amended) A method of making an FED, comprising:  
making a cathode assembly, making an anode assembly, and assembling the cathode and the  
anode assemblies,  
wherein ~~said step of~~ making a cathode assembly comprises:  
providing a substrate;  
forming an emitter electrode structure on the substrate;  
forming a resistive layer over the emitter electrode structure;  
forming an insulative layer on a portion of the resistive layer;  
forming at least one micropoint emitter on the substrate and in contact with both the resistive  
layer and the insulative layer;  
forming a conductive grid structure spaced from the at least one micropoint emitter; and  
forming a dielectric structure spaced from the at least one micropoint emitter and between the  
insulative layer and the grid structure.

27. (Currently Amended) The method of Claim 26 wherein ~~said~~the emitter electrode  
structure comprises metal strips.

28. (Currently Amended) The method of Claim 26 wherein ~~said~~the emitter electrode  
structure comprises aluminum strips.

29. (Currently Amended) The method of Claim 28 wherein ~~said~~the aluminum strips  
have a thickness of about 1000 Å.

30. (Currently Amended) The method of Claim 26 wherein ~~said~~the insulative layer  
comprises silicon oxide.

31. (Currently Amended) The method of Claim 26 wherein ~~said~~the insulative layer comprises silicon nitride.